

TECHNICAL SPECIFICATION

IEC 61158-4

First edition
1999-03

**Digital data communications for
measurement and control –
Fieldbus for use in industrial control systems –**

**Part 4:
Data Link protocol specification**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**DIGITAL DATA COMMUNICATIONS FOR MEASUREMENT AND CONTROL –
FIELDBUS FOR USE IN INDUSTRIAL CONTROL SYSTEMS –**

Part 4 : Data Link protocol specification

FOREWORD

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IEC 61158-4, which is a technical specification, has been prepared by subcommittee 65C: Digital communications, of IEC technical committee 65: Industrial-process measurement and control.

The text of this technical specification is based on the following documents:

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Full information on the voting for the approval of this technical specification can be found in the report on voting indicated in the above table.